

UMW SET23A12L02-E18

1.Description

SET23A12L02-E18 is designed to protect components which are connected to data and transmission lines from voltage surges caused by electrostatic discharge (ESD), electrical fast transients (EFT) and lightning. TVS diodes are characterized by their high surge capability, low operating and clamping voltages, and fast response time.

3.Features

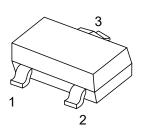
- IEC61000-4-2 ESD 30KV Air, 30KV contact compliance
- Protects one bidirectional line or two unidirectional lines
- Working voltage: 12V

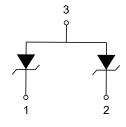
2.Applications

- Cellular handsets and accessories
- Personal digital assistants (PDA's)
- Portable instrumentation
- Set Top Box (STB)
- Servers, notebook, and desktop PC
- Wireless bus protection
- RS-232, RS-422, RS-423 protection

- Low leakage current
- Low operating and clamping voltages
- Solder reflow temperature: Pure Tin-Sn, 260~270°C

4.Pinning information





SOT-23







5.Absolute Maximum Ratings

Parameter	Symbol	Value	Units
Peak Pulse Power (t _p =8/20µs waveform)	P _{PP}	500	W
ESD voltage (Contact discharge)		±30	kV
ESD voltage (Air discharge)	V_{ESD}	±30	kV
Storage & junction temperature range	T_J, T_{STG}	-55 to 150	°C







6.Electrical Characteristics(T_J=25°C)

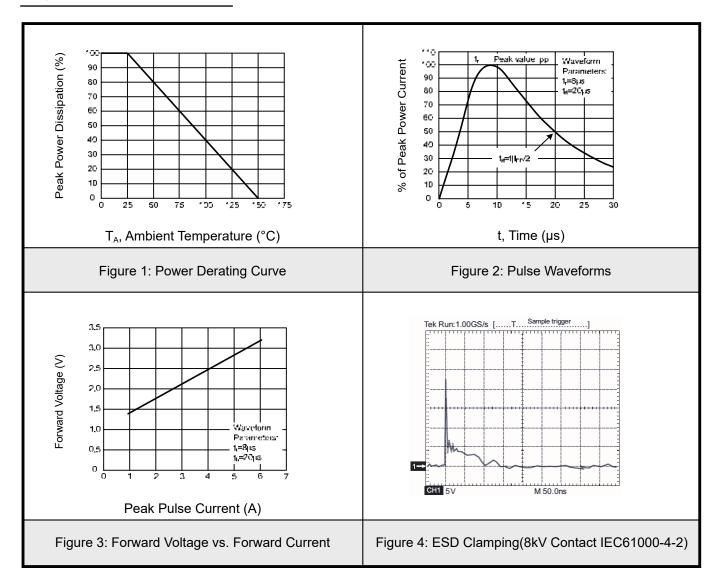
Parameter	Symbol	Conditions	Min	Тур	Max	Units
Reverse Stand-Off Voltage	V_{RWM}				12	V
Reverse Breakdown Voltage	V_{BR}	I _{BR} =1mA	13.3			V
Reverse Leakage Current	I _R	V _R =12V, Each I/O pin			1	μΑ
Clamping voltage (t _p =8/20µs)	Vc	I _{PP} =1A			19	V
Clamping voltage (t _p =8/20µs)	V _C	I _{PP} =18A			27	V
Off state junction capacitance	Сл	0Vdc,f=1MHz Between I/O pins and GND		100		pF







7. Typical characteristic



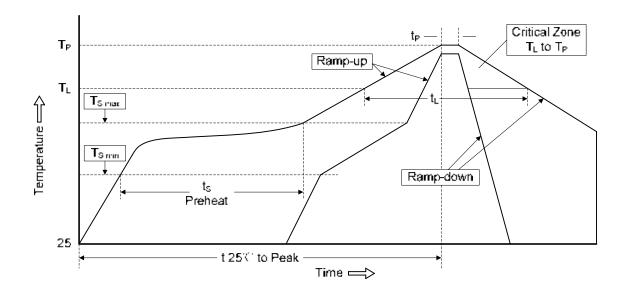






8.Recommended Soldering Conditions

	Reflow Condition	Pb-Free Assembly		
	-Temperature Min (T _{s(min)})	150°C		
Pre Heat	-Temperature Max (T _{s(max)})	200°C		
	-Time (Min to Max) (t _s)	60-180 secs.		
Average ramp-up ra	ate (T∟ to T _P)	3°C/sec. Max		
$T_{s(max)}$ to T_L - Ramp-	up Rate	3°C/sec. Max		
Time maintained	-Temperature(T _L)	217°C		
above:	-Time(T _L)	60-150 secs.		
Peak Temp (Tp)		260°C		
Time within 5°C of	actual Peak Temp (Tp)	20-40 seconds		
Ramp-down Rate		6°C/sec. Max		
Time 25°C to Peak	Temperature	8 min. Max		

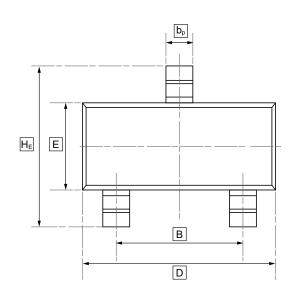


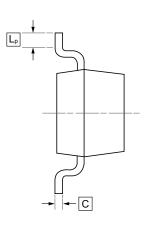


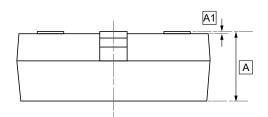




9.SOT-23 Package Outline Dimensions







DIMENSIONS (mm are the original dimensions)

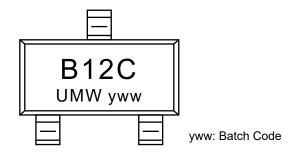
Symbol	Α	В	þр	С	D	E	HE	A1	Lp
Min	0.95	1.78	0.35	0.08	2.70	1.20	2.20	0.013	0.20
Max	1.40	2.04	0.50	0.19	3.10	1.65	3.00	0.100	0.50







10.Ordering information



Order Code	Package	Base QTY	Delivery Mode		
UMW SET23A12L02-E18	SOT-23	3000	Tape and reel		







11.Disclaimer

UMW reserves the right to make changes to all products, specifications. Customers should obtain the latest version of product documentation and verify the completeness and currency of the information before placing an order.

When applying our products, please do not exceed the maximum rated values, as this may affect the reliability of the entire system. Under certain conditions, any semiconductor product may experience faults or failures. Buyers are responsible for adhering to safety standards and implementing safety measures during system design, prototyping, and manufacturing when using our products to prevent potential failure risks that could lead to personal injury or property damage.

Unless explicitly stated in writing, UMW products are not intended for use in medical, life-saving, or life-sustaining applications, nor for any other applications where product failure could result in personal injury or death. If customers use or sell the product for such applications without explicit authorization, they assume all associated risks.

When reselling, applying, or exporting, please comply with export control laws and regulations of China, the United States, the United Kingdom, the European Union, and other relevant countries, regions, and international organizations.

This document and any actions by UMW do not grant any intellectual property rights, whether express or implied, by estoppel or otherwise. The product names and marks mentioned herein may be trademarks of their respective owners.